

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | User Part Number | | | | | | |
|--|---|---|-----------------------------------|-----------|------------|-----------|--|--|
| | | BZX84-A75-Q | | | | | | |
| | | Part Description | | | | | | |
| | | Nexperia DHAM | | | | | | |
| | | SMD package | | | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST Pre- and Post-Stress | | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| # A1 | PC Preconditioning | JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering | 24 hours 168 hours 3 cycles | 1514 | 64430 | 0 | | |
| # B1 | HTRB | MIL-STD-750-1 M1038 Method A Tj = Tjmax, VR = 80 % of rated reverse voltage | 1000 hours | 250 | 11400 | 0 | | |
| # B1b | SSOP Steady State Operational | MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current | 1000 hours | 44 | 1920 | 0 | | |
| # A4 | TC Temperature Cycling | JESD22-A104 -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 311 | 14080 | 0 | | |
| # A3 or | UHAST Unbiased HAST | JESD22-A118 Tamb = 130 °C, RH = 85 % JESD22-A102 | —96 hours | 311 | 14080 | 0 | | |
| # A3 alt | AC Autoclave | Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia) | | | | | | |
| " A2 II | H3TRB High Humidity High | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of | 1000 | 244 | 1 1000 | | | |
| # A2 alt | Temperature Reverse Bias | MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = | 1000 hours | 311 | 14080 | 0 | | |
| # A5 | Intermittent Operating Life | , . | 1000 hours | 312 | 14120 | 0 | | |
| # C8 | RSH Resistance to Solder Heat | JESD22-A111 260 °C ± 5 °C | 10 s | 269 | 8070 | 0 | | |
| # C10 | SD Solderability | J-STD-002 | | 19 | 6660 | 0 | | |

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Zener | 11400 | 0 | 0,37 | 2,68E+09 |

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